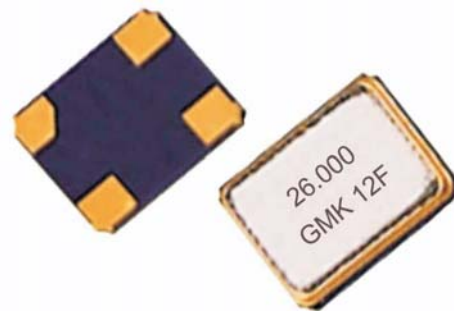


FEATURE

- Ultra thin, thickness 1.0mm
- Leadless type
- High precision characteristic covering up to high frequency range
- Designed for automatic mounting and reflow soldering
- Embossed taping specification
- The best choice of Bluetooth wireless communication sets, DSN, PDA and mobile phone



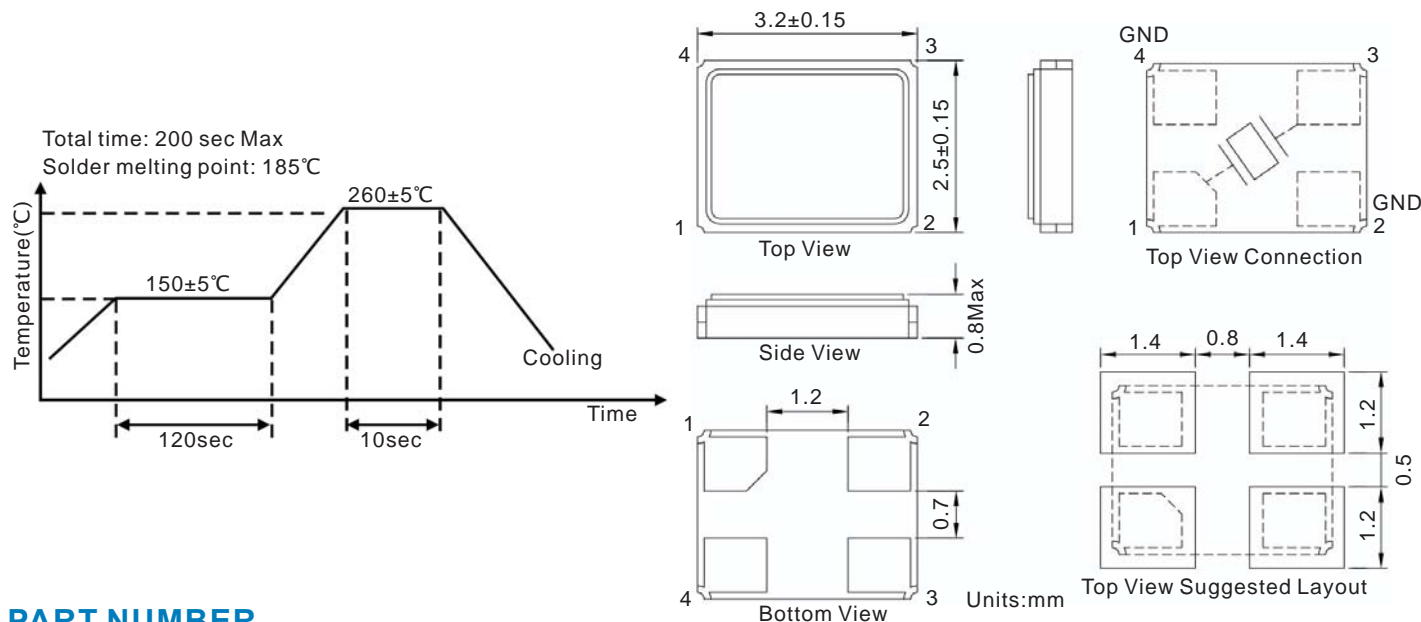
ELECTRICAL SPECIFICATIONS

Frequency Range	12.000MHz to 54.000MHz
Frequency Tolerance	±10ppm to ±100ppm @25°C
Frequency Stability	±10ppm to ±100ppm
Load Capacitance(C _L)	18pF, 20pF, or specify
Equivalent Series Resistance	See below table
Operating Temperature Range	-20°C to +70°C (typical), -10°C to +60°C, -40°C to +85°C
Storage Temperature Range	-40°C to +85°C / -55°C to +125°C
Shunt Capacitance(C ₀)	7.0pF Max
Drive Level(Typical)	10μW Typical
Aging @25°C 1 st year (Max)	±5ppm/year
Insulation Resistance	More than 500MΩ at DC100V

EQUIVALENT SERIES RESISTANCE(ESR) AND OSCILLATION MODE

Frequency(MHz)	E.S.R(Ω)	Mode	Frequency(MHz)	E.S.R(Ω)	Mode
12.000~15.999	100Max	Fundamental	20.000~23.999	60Max	Fundamental
16.000~19.999	80Max	Fundamental	24.000~54.000	40Max	Fundamental

DIMENSIONS AND REFLOW CONDITION



PART NUMBER

GMK-SSMD3225-	26.000	20	30	B	30	40
	Frequency 26.000 26.000MHz	Load Cap. 20:20pF 00:Series	Frequency Tolerance 30:±30ppm	Operating Temperature A:-10~60°C B:-20~70°C C:-40~85°C	Frequency Stability 30:±30ppm	E.S.R. Max 40:40Ω